#### FINAL

# Am27H256

256 Kilobit (32,768 x 8-Bit) High Speed CMOS EPROM

Advanced Micro **Devices** 

## DISTINCTIVE CHARACTERISTICS

- **■** Fast access time
  - 35 ns
- **■** JEDEC-approved pinout
  - Pin compatible with Am27C256
- Single +5 V power supply
- ±10% power supply tolerance available

- 100% Flashrite<sup>TM</sup> programming
  - Typical programming time of 4 seconds
- Latch-up protected to 100 mA from -1 V to Vcc + 1 V
- High noise immunity
- Standard 28-pin DIP, PDIP, 32-pin LCC and PLCC packages
- DESC SMD No. 5962-86063

#### **GENERAL DESCRIPTION**

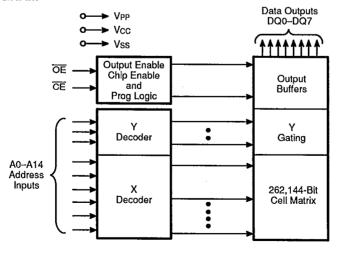
The Am27H256 is an 256 Kbit ultraviolet erasable programmable read-only memory. It is organized as 32K words by 8 bits per word, operates from a single +5 V supply, and features fast single address location programming. Products are available in windowed ceramic DIP and LCC packages as well as plastic one time programmable (OTP) PDIP and PLCC packages.

Typically, any byte can be accessed in less than 35 ns. allowing operation with high-performance microprocessors without any WAIT states. The Am27H256 offers separate Output Enable (OE) and Chip Enable (CE) controls, thus eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 220 mW in active mode, and 50 mW in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks. or at random. The Am27H256 supports AMD's Flashrite™ programming algorithm (100 us pulses) resulting in typical programming time of 4 seconds.

#### **BLOCK DIAGRAM**



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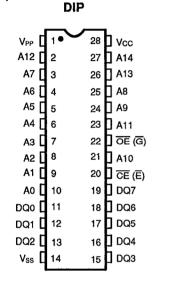


#### PRODUCT SELECTOR GUIDE

Family Part No.	Am27	H256
Ordering Part Number Vcc ± 5%	-35V05	
Vcc ± 10%	-35	-45
Max Access Time (ns)	35	-45
CE (E) Access Time (ns)	35	-45
OE (G) Access Time (ns)	20	20

#### **CONNECTION DIAGRAMS**

## **Top View**

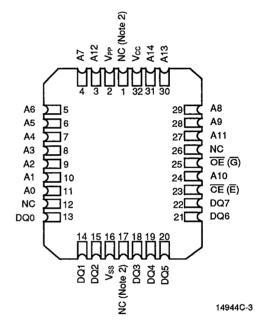


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#### Notes:

- 1. JEDEC nomenclature is in parentheses.
- 2. Don't use (DU) for PLCC.

## PLCC/LCC



#### PIN DESIGNATIONS

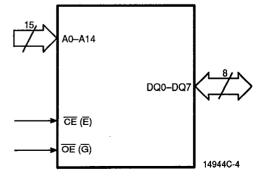
A0-A14 Address Inputs CE(E) Chip Enable DQ0-DQ7 Data Inputs/Outputs NC No Internal Connection OE (G) Output Enable Input

Vcc Vcc Supply Voltage

Program Supply Voltage  $V_{PP}$ 

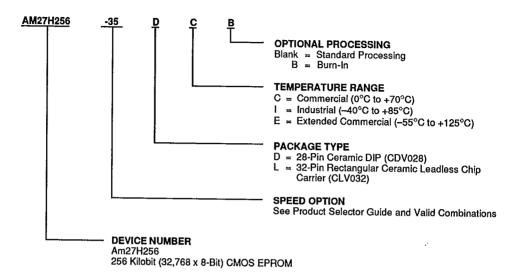
Vss Ground

## **LOGIC SYMBOL**



## ORDERING INFORMATION **EPROM Products**

AMD Standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:



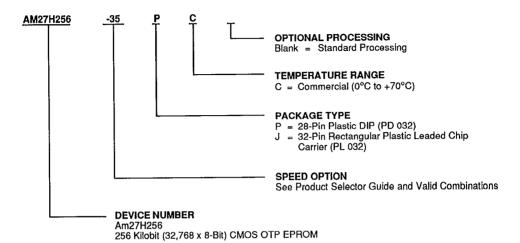
Valid Combinations				
AM27H256-35	DC, DCB, DI, DIB,			
AM27H256-35V05	LC, LI, LCB, LIB			
AM27H256-45	DC, DCB, DE, DEB, DI, DIB, LC, LCB, LI, LIB, LE, LEB			

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

## ORDERING INFORMATION **OTP Products**

AMD Standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:



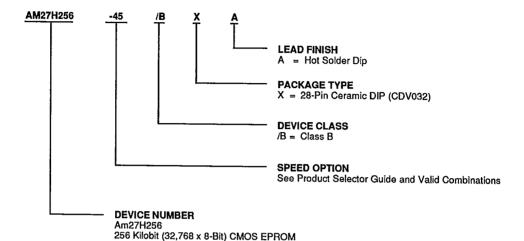
Valid Combinations					
AM27H256-35V05	- IO				
AM27H256-45	6-45 PC, JC				

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

## **ORDERING INFORMATION** Military APL Products

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883 requirements. The order number (Valid Combination) is formed by a combination of:



Valld Combinations					
AM27H256-45 /BXA, /BUA					

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

#### **Group A Tests**

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

## **FUNCTIONAL DESCRIPTION** Erasing the Am27H256

In order to clear all locations of their programmed contents, it is necessary to expose the Am27H256 to an ultraviolet light source. A dosage of 15 W seconds/cm2 is required to completely erase an Am27H256. This dosage can be obtained by exposure to an ultraviolet lamp-wavelength of 2537 A-with intensity of 12,000 µW/cm2 for 15 to 20 minutes. The Am27H256 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27H256 and similar devices will erase with light sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than with UV sources at 2537 Å, exposure to fluorescent light and sunlight will eventually erase the Am27H256 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

### Programming the Am27H256

Upon delivery or after each erasure the Am27H256 has all 262,144 bits in the "ONE" or HIGH state. "ZEROs" are loaded into the Am27H256 through the procedure of programming.

The programming mode is entered when 12.75 V  $\pm$ 0.25 V is applied to the VPP pin, CE is at VIL and OE is at Vin.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins.

The Flashrite algorithm reduces programming time by using 100 µs programming pulses and by giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data does not verify, additional pulses are given until it verifies or the maximum is reached. This process is repeated while sequencing through each address of the Am27H256. This part of the algorithm is done at Vcc = 6.25 V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. After the final address is completed, the entire EPROM memory is verified at  $V_{CC} = V_{PP} = 5.25 \text{ V}$ .

Please refer to Section 6 for programming flow chart and characteristics.

## **Program Inhibit**

Programming of multiple Am27H256 in parallel with different data is also easily accomplished. Except for CE,

all like inputs of the parallel Am27H256 may be common. A TTL low-level program pulse applied to an Am27H256  $\overline{\text{CE}}$  input with  $V_{PP} = 12.75 \text{ V} \pm 0.25 \text{ V}$  and  $\overline{\text{OE}}$ high, will program that Am27H256. A high-level CE input inhibits the other Am27H256 devices from being proarammed.

### **Program Verify**

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with OE at VIL, CE at VIH and Vpp between 12.5 V and 13.0 V.

#### **Auto Select Mode**

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ± 5°C ambient temperature range that is required when programming the Am27H256.

To activate this mode, the programming equipment must force 12.0 V  $\pm$  0.5 V on address line A9 of the Am27H256. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from VIL to VIH. All other address lines must be held at VIL during auto select mode.

Byte 0 (A0 = VIL) represents the manufacturer code, and byte 1 (A0 = V<sub>IH</sub>), the device code. For the Am27H256, these two identifier bytes are given in the Mode Select Table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit.

#### **Read Mode**

The Am27H256 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Assuming that addresses are stable, address access time (tACC) is equal to the delay from  $\overline{CE}$  to output (t<sub>CE</sub>). Output Enable ( $\overline{OE}$ ) is the output control and should be used to gate data to the output pins, independent of device selection. Data is available at the outputs toE after the falling edge of OE, assuming that CE has been LOW and addresses have been stable for at least tACC - tOE.

### Standby Mode

The Am27H256 has a standby mode which reduces the maximum Vcc current to 50% of the active current. It is placed in standby mode when CE is at VIH. The amount of current drawn in standby mode depends on the frequency and the number of address pins switching. The Am27H256 is specified with 50% of the address lines togaling at 10 MHz. A reduction of the frequency or quantity of address lines toggling will significantly reduce actual standby current.

## **Output OR-Tieing**

To accommodate multiple memory connection, a twoline control function is provided to allow for:

- Low memory power dissipation
- Assurance that output bus contention will not occur

It is recommended that  $\overline{\text{CE}}$  be decoded and used as the primary device-selecting function, while OE be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

## **System Applications**

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1-uF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between Vcc and Vss to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7- $\mu F$  bulk electrolytic capacitor should be used between Vcc and Vss for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

#### MODE SELECT TABLE

Mode	Pins	ČE	OE	AO	A9	V <sub>PP</sub>	Outputs
Read		VıL	ViL	A0	A9	Vcc	Dout
Output Disable		VIL	Vін	Х	Х	Vcc	Hi-Z
Standby		ViH	Х	Х	Х	Vcc	Hi-Z
Program		ViL	VIH	Х	Х	Vep	Din
Program Verify		ViH	VIL	Х	Х	VPP	D <sub>OUT</sub>
Program Inhibit		ViH	ViH	Х	Х	VPP	Hi-Z
Auto Select	Manufacturer Code	VíL	VIL	VIL	VH	Vcc	01H
(Note 3)	Device Code	ViL	VIL	VIH	VH	V <sub>CC</sub>	10H

#### Notes:

- 1.  $VH = 12.0 V \pm 0.5 V$
- 2. X = Either VIH or VII
- 3. A1-A8 = A10-A14 = Vil
- 4. The Am27H256 uses the same Flashrite algorithm during programming as the Am27C256.

### **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature         -65°C to +125°C           All Other Products         -65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Voltage with Respect to $V_{SS}$ All pins except A9, $V_{PP}$ , $V_{CC}$ $-0.6$ V to $V_{CC}$ +0.5 V (Note 1)
A9 and V <sub>PP</sub> (Note 2)0.6 V to +13.5 V
Vcc0.6 V to +7.0 V

#### Notes:

- 1. Minimum DC voltage on input or I/O pins is -0.5 V. During transitions, the inputs may overshoot Vss to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O pins is Vcc + 0.5 V which may overshoot to Vcc + 2.0 V for periods up to 20 ns.
- 2. For A9 and VPP the minimum DC input is -0.5 V. During transitions, A9 and VPP may overshoot Vss to -2.0 V for periods of up to 20 ns. A9 and VPP must not exceed 13.5 V for any period of time.

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

#### **OPERATING RANGES**

Commercial (C) Devices Case Temperature (Tc) 0°C to +70°C
Industrial (I) Devices  Case Temperature (Tc)40°C to +85°C
Extended Commercial (E) Devices  Case Temperature (Tc)55°C to +125°C
Military (M) Devices  Case Temperature (Tc) –55°C to +125°C
Supply Read Voltages Vcc for Am27H256-XXV05 +4.75 V to +5.25 V
Vcc for Am27H256-XX0 +4.50 V to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

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DC CHARACTERISTICS over operating range unless otherwise specified. (Notes 1, 2, 3 and 4) (for APL Products, Group A, Subgroups 1, 2, 3, 7 and 8 are tested unless otherwise noted)

Parameter Symbol	Parameter Description	Test Conditions		Min	Max	Unit
Vон	Output HIGH Voltage	10H = -4 mA		2,4	<del></del>	V
Vol	Output LOW Voltage	IOL = 12 mA			0.45	V
ViH	Input HIGH Voltage			2.0	Vcc + 0.5	
VIL	Input LOW Voltage			-0.3	+0.8	V
lu	In Jacob and Comment		C/I Devices	· <u>-</u>	1.0	
ILI Input Load Current	ViN = 0 V to +Vcc	E/M Devices		1.0	μА	
lto	Output Lookens Comment		C/I Devices		10.0	
	Output Leakage Current	Vout = 0 V to +Vcc	E/M Devices		10.0	μΑ
lcc1	Vcc Active Current	CE = VIL, f = 10 MHz	C/I Devices		50	
	(Note 3)	IOUT = 0 mA	E/M Devices		60	mA
ICC2	Vcc Standby Current	CE = VIH	C/I Devices		25	mA
			E/M Devices		35	IIIA
IPP1	VPP Current During Read	CE = OE = VIL, VPP = V	-	100	μА	

#### Notes:

- 1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$ , and removed simultaneously or after  $V_{PP}$ .
- 2. Caution: The Am27H256 must not be removed from (or inserted into) a socket when Vcc or VPP is applied.
- 3.  $I_{CC1}$  is tested with  $\overline{OE}/V_{PP} = V_{IH}$  to simulate open outputs.
- Minimum DC Input Voltage is −0.5 V. During transitions, the inputs may overshoot to −2.0 V for periods less than 20 ns.
   Maximum DC Voltage on output pins is V<sub>CC</sub> + 0.5 V, which may overshoot to V<sub>CC</sub> + 2.0 V for periods less than 20 ns.

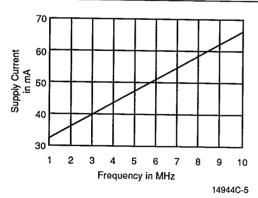


Figure 1. Typical Supply Current vs. Frequency Vcc = 5.0 V, T = 25°C

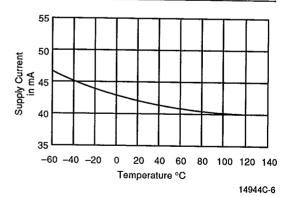


Figure 2. Typical Supply Current vs. Temperature Vcc = 5.0 V, f = 10 MHz



#### CAPACITANCE

Parameter		Test	CD	/028	CL	V032	PD	028	PL	032	
Symbol	Parameter Description	Conditions	Тур	Max	Тур	Max	Тур	Max	Тур	Max	Unit
CIN	Input Capacitance	Vin = 0	6	12	6	12	8	12	8	12	рF
Cour	Output Capacitance	Vout = 0	8	15	6	15	10	15	10	15	pF

#### Notes:

- 1. This parameter is only sampled and not 100% tested.
- 2.  $T_A = +25^{\circ}C$ , f = 1 MHz.

## SWITCHING CHARACTERISTICS over operating range unless otherwise specified (Notes 1, 3 and 4) (for APL Products, Group A, Subgroups 9,10 and 11 are tested unless otherwise noted)

Parameter Symbols JEDEC Standard					Am27ł	1256
		Parameter Description	Test Conditions	-35V05 -35	-45	
TAVQV	trcc	Address to	CE = OE = VII	Min		
IAVQV	THEC	Output Delay	$C_L = C_{L1}$	Max	35	45
tELQV	tce	Chip Enable to	OE = V <sub>IL</sub>	Min		
LLC		Output Delay	$C_L = C_{L1}$	Max	35	45
tgLov	toE	Output Enable to	CE ≈ V <sub>IL</sub>	Min		
·uLuv	Output Delay		$C_L = C_{L1}$	Max	20	20
tenoz.	tor	Chip Enable HIGH or	$C_L = C_{L2}$	Min	0	0
tgHQZ	(Note 2)	Output Enable HIGH, whichever comes first, to Output Float		Max	20	20
taxox	ton	Output Hold from		Min	0	0
		Addresses, CE, or OE, whichever occurred first		Max		

#### Notes:

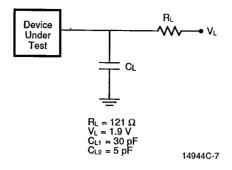
- 1. VCC must be applied simultaneously or before VPP, and removed simultaneously or after VPP.
- 2. This parameter is only sampled and not 100% tested.
- 3. Caution: The Am27H256 must not be removed from (or inserted into) a socket or board when VPP or Vcc is applied.
- 4. Output Load: 1 TTL gate and C = CL

Input Rise and Fall Times: 5 ns

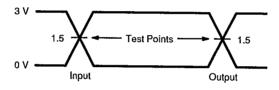
Input Pulse Levels: 0 V to 3 V.

Timing Measurement Reference Level: 1.5 V for inputs and outputs

## **SWITCHING TEST CIRCUIT**



## **SWITCHING TEST WAVEFORM**



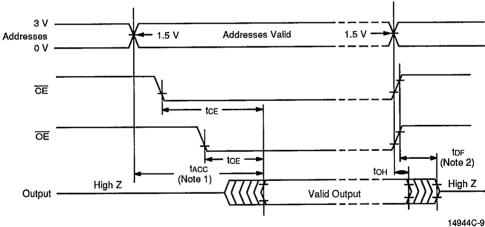
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AC Testing: Inputs are driven at 3.0 V for a logic "1" and 0 V for a logic "0." Input pulse rise and fall times are ≤ 5 ns.

### **KEY TO SWITCHING WAVEFORMS**

WAVEFORM	INPUTS	OUTPUTS
	Must Be Steady	Will Be Steady
	May Change from H to L	Will Be Changing from H to L
	May Change from L to H	Will Be Changing from L to H
	Don't Care, Any Change Permitted	Changing State Unknown
<b>&gt;&gt;</b>	Does Not Apply	Center Line is High Impedence "Off" State
<del></del>		KS00001

#### **SWITCHING WAVEFORMS**



#### Notes:

- 1.  $\overrightarrow{OE}$  may be delayed up to tacc toe after the falling edge of the addresses without impact on tacc.
- 2. tDF is specified from  $\overline{OE}$  or  $\overline{CE}$ , whichever occurs first.